

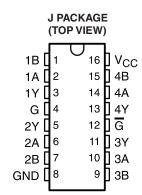
# QML CLASS V RS-422 QUADRUPLE DIFFERENTIAL LINE RECEIVER

Check for Samples: AM26LS33A-SP

#### **FEATURES**

- AM26LS33A Devices Meet or Exceed the Requirements of ANSI TIA/EIA-422-B, TIA/EIA-423-B, and ITU Recommendations V.10 and V.11
- ±15-V Common-Mode Range With ±500-mV Sensitivity
- Input Hysteresis . . . 50 mV Typical
- Operate From a Single 5-V Supply
- Low-Power Schottky Circuitry
- 3-State Outputs
- Complementary Output-Enable Inputs
- Input Impedance . . . 12 kΩ Minimum
- Designed to Be Interchangeable With Advanced Micro Device AM26LS33™
- QML-V Qualified, SMD 5962-78020
- Military Temperature Range (-55°C to 125°C)

• Rad-Tolerant: 25 kRad (Si) TID (1)



(1) Radiation tolerance is a typical value based upon initial device qualification with dose rate = 10 mrad/sec. Radiation Lot Acceptance Testing is available - contact factory for details.

### **DESCRIPTION**

The AM26LS33A is a quadruple differential line receiver for balanced and unbalanced digital data transmission. The enable function is common to all four receivers and offers a choice of active-high or active-low input. The 3-state outputs permit connection directly to a bus-organized system. Fail-safe design ensures that, if the inputs are open, the outputs always are high.

Compared to the AM26LS33, the AM26LS33A incorporates an additional stage of amplification to improve sensitivity. The input impedance has been increased, resulting in less loading of the bus line. The additional stage has increased propagation delay; however, this does not affect interchangeability in most applications.

The AM26LS33A is characterized for operation over the temperature range of -55°C to 125°C.

## ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	CDIP - J	5962-7802007VEA	5962-7802007VEA

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

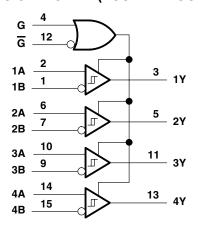
**INSTRUMENTS** 

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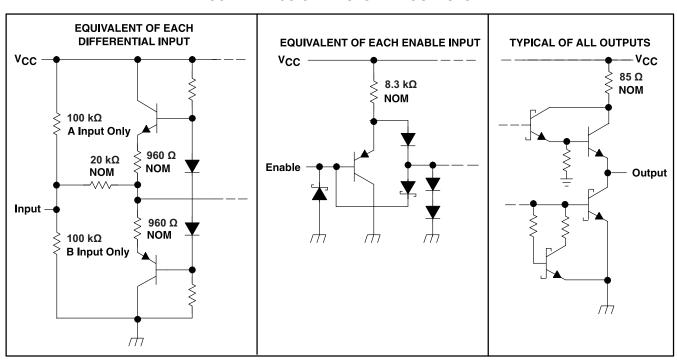
Table 1. FUNCTION TABLE Each Receiver

DIFFERENTIAL	ENA	OUTPUT	
A–B	G	G	Y
V >V	Н	X	Н
$V_{ID} \ge V_{IT+}$	X	L	Н
V	Н	X	?
$V_{IT-} \leq V_{ID} \leq V_{IT+}$	X	L	?
V	Н	Χ	L
$V_{ID} \le V_{IT-}$	X	L	L
X	L	Н	Z
Onon	Н	X	Н
Open	X	L	Н

## **LOGIC DIAGRAM (POSITIVE LOGIC)**



## **SCHEMATICS OF INPUTS AND OUTPUTS**



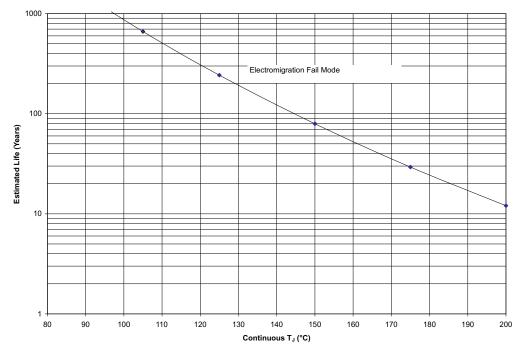


## ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN MAX	UNIT
$V_{CC}$	Supply voltage (2)		7	V
VI	land to the land	Any differential input	±25	
	Input voltage	Other inputs	7	V
$V_{ID}$	Differential input voltage (3)		±25	V
	Continuous total power dissipation		See Dissipation Ratings Table	
	Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds		300	°C
T <sub>stg</sub>	Storage temperature range		<b>-65</b> 150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the network ground terminal.
- (3) Differential voltage values are at the noninverting (A) input terminals with respect to the inverting (B) input terminals.



- A. See datasheet for absolute maximum and minimum recommended operating conditions.
- B. Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).

Figure 1. AM26LS33A 16/J Package Operating Life Derating Chart



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## RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			8.0	V
$V_{IC}$	Common-mode input voltage			±15	V
I <sub>OH</sub>	High-level output current			-440	μΑ
I <sub>OL</sub>	Low-level output current			8	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	°C

## **ELECTRICAL CHARACTERISTICS**

over recommended ranges of  $V_{CC}$ ,  $V_{IC}$ , and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS			TYP <sup>(1)</sup>	MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage	$V_O = V_{OH} min$ , $I_{OH} = -440 \mu A$ -15 V $\leq$ VIC $\leq$ 15 V				0.5	V
V <sub>IT-</sub>	Negative-going input threshold voltage	$V_{O} = 0.45 \text{ V}$ , $I_{OL} = 8 \text{ mA}$ -15 V $\leq$ VIC $\leq$ 15 V		-0.5 <sup>(2)</sup>			V
V <sub>hys</sub>	Hysteresis voltage (V <sub>IT+</sub> – V <sub>IT-</sub> )				50		mV
$V_{IK}$	Enable-input clamp voltage	$V_{CC} = 4.5 V,$	$I_I = -18 \text{ mA}$			-1.5	V
V <sub>OH</sub>	High-level output voltage	$V_{CC} = 4.5 \text{ V}, V_{ID} = 1 \text{ V}, V_{IG} = 0.8 \text{ V}, I_{OH} = -440 \mu\text{A}$		2.5			V
V	Low-level output voltage	$V_{CC} = 4.5 \text{ V}, V_{ID} = -1 \text{ V}, V_{IG} = 0.8 \text{ V}$	I <sub>OL</sub> = 4 mA			0.4	V
V <sub>OL</sub>			I <sub>OL</sub> = 8 mA			0.45	
	Off-state		V <sub>O</sub> = 2.4 V			20	
l <sub>OZ</sub>	(high-impedance state) output current	V <sub>CC</sub> = 5.5 V	V <sub>O</sub> = 0.4 V			-20	μΑ
	Line input current	V <sub>I</sub> = 15 V,	Other input at -10 V to 15 V			1.2	A
I <sub>I</sub>		$V_I = -15 \text{ V},$	Other input at -15 V to 10 V			-1.7	mA
I <sub>I(EN)</sub>	Enable input current	V <sub>I</sub> = 5.5 V, V <sub>CC</sub> = 5.5 V				100	μΑ
I <sub>H</sub>	High-level enable current	$V_{I} = 2.7 \text{ V}, V_{CC} = 5.5 \text{ V}$				20	μΑ
IL	Low-level enable current	V <sub>I</sub> = 0.4 V, V <sub>CC</sub> = 5.5 V				-0.36	mA
rį	Input resistance	$V_{IC} = -15 \text{ V to } 15 \text{ V},$	One input to ac ground	12	15		kΩ
los	Short-circuit output current (3)	$V_{CC} = MAX$ , $V_{ID} = 1$ V, $V_{O} = 0$ V		-15		-85	mA
I <sub>CC</sub>	Supply current	V <sub>CC</sub> = MAX, data inputs = GND,	All outputs disabled		52	70	mA

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 <sup>(1)</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C, and V<sub>IC</sub> = 0.
 (2) The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold levels only.

Not more than one output should be shorted to ground at a time, and duration of the short circuit should not exceed one second.



## **SWITCHING CHARACTERISTICS**

 $V_{CC}$  = 5 V, over operating free-air temperature (unless otherwise noted)

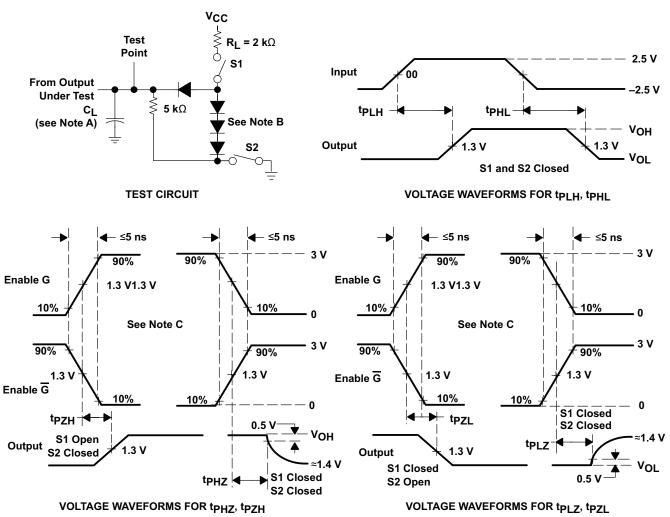
	PARAMETER	TEST	TEST CONDITIONS			MAX	UNIT	
	Propagation delay time, low-to-high-level	C <sub>L</sub> = 15 pF,	See Figure 2		20	35	20	
t <sub>PLH</sub>	output	C <sub>L</sub> = 15 pr,	$T_A = -55$ °C to 125°C			53	ns	
	Propagation delay time, high-to-low-level	C 15 pF	See Figure 2		22	35	20	
t <sub>PHL</sub>	output	$C_L = 15 \text{ pF},$	$T_A = -55$ °C to 125°C			53	ns	
	Output enable time to high level	C <sub>L</sub> = 15 pF,	See Figure 2		17	25	ns	
t <sub>PZH</sub>			$T_A = -55$ °C to 125°C			38		
	Output analysis for a tallow lavel	0 45 -5	See Figure 2		20	25		
t <sub>PZL</sub>	Output enable time to low level	$C_L = 15 \text{ pF},$	$T_A = -55$ °C to 125°C			38	ns	
	Output Packle Constraint land	0 45 -5	See Figure 2		21	30		
t <sub>PHZ</sub>	Output disable time from high level	$C_L = 15 pF,$	$T_A = -55$ °C to 125°C			45	ns	
t <sub>PLZ</sub>	Outside disable the form form levels and	0 45 -5	See Figure 2		30	40		
	Output disable time from low level	$C_L = 15 \text{ pF},$	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			60	ns	

<sup>(1)</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C, and  $V_{IC}$  = 0.

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## PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. All diodes are 1N3064 or equivalent.

C. Enable G is tested with  $\overline{G}$  high;  $\overline{G}$  is tested with G low.

Figure 2. Test Circuit and Voltage Waveforms



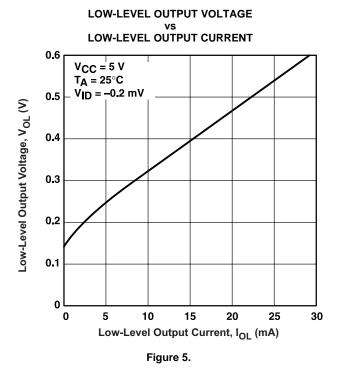
## TYPICAL CHARACTERISTICS

## HIGH-LEVEL OUTPUT VOLTAGE HIGH-LEVEL OUTPUT CURRENT 5 $V_{ID} = 0.2 V$ $T_{\Delta} = 25^{\circ}C$ High-Level Output Voltage, VOH (V) 3 V<sub>CC</sub> = 5.25 V V<sub>CC</sub> = 5 V 2 V<sub>CC</sub> = 5.5 V V<sub>CC</sub> = 4.75 V 1 V<sub>CC</sub> = 4.5 V 0 -10 -20 -30 -40 -50

 $\ensuremath{^{\dagger}}\ensuremath{\,\text{V}_{CC}}\xspace = 5.5\ \mbox{V}$  and  $\ensuremath{\,\text{V}_{CC}}\xspace = 4.5\ \mbox{V}$  applies to M-suffix devices only.

High-Level Output Current, IOH (mA)

#### Figure 3.



# HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

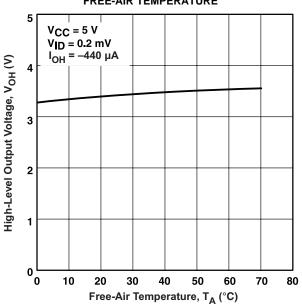


Figure 4.

# LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

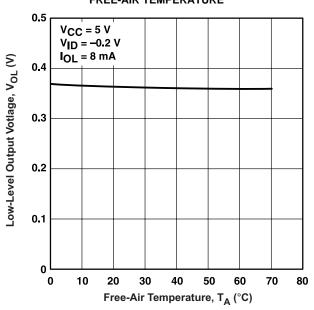


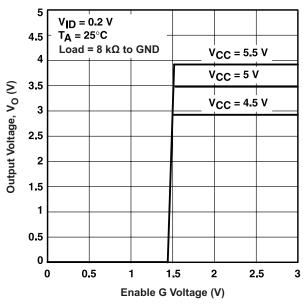
Figure 6.



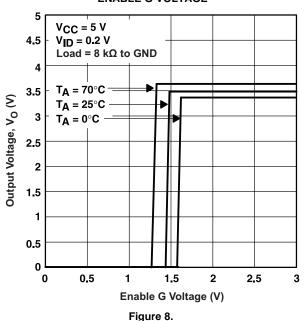


## **TYPICAL CHARACTERISTICS (continued)**





OUTPUT VOLTAGE vs ENABLE G VOLTAGE



#### Figure 7.

# OUTPUT VOLTAGE vs ENABLE G VOLTAGE

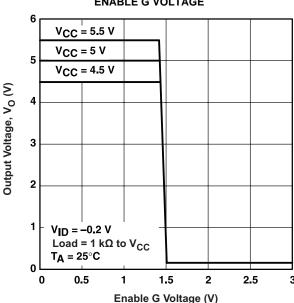


Figure 9.

OUTPUT VOLTAGE vs ENABLE G VOLTAGE

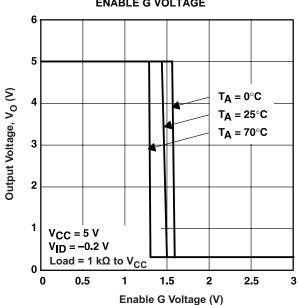
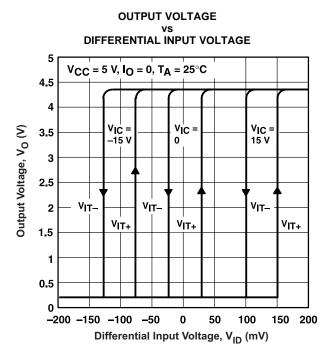
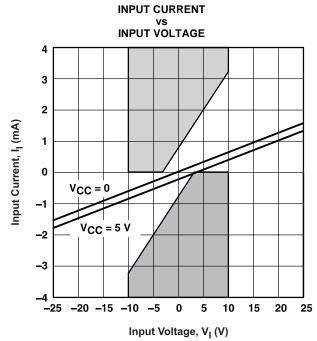


Figure 10.



# **TYPICAL CHARACTERISTICS (continued)**





The unshaded area shows requirements of paragraph 4.2.1 of ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B.

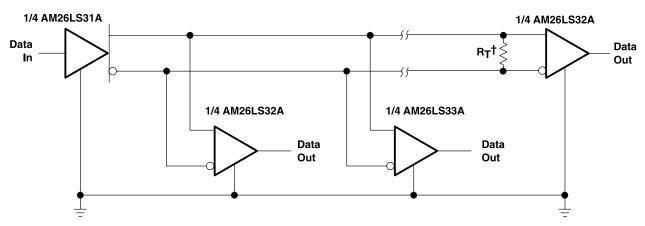
Figure 12.

Figure 11.

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## **APPLICATION INFORMATION**



<sup>†</sup>R<sub>T</sub> equals the characteristic impedance of the line.

Figure 13. Circuit with Multiple Receivers



23-Mar-2012

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-7802007VEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF AM26LS33A-SP:

Catalog: AM26LS33A

Military: AM26LS33AM

NOTE: Qualified Version Definitions:



23-Mar-2012

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## 14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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